

TK7A50D



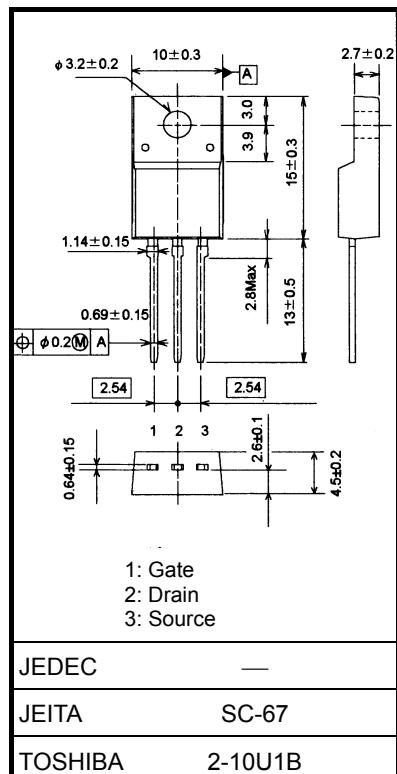
Switching Regulator Applications

Unit: mm

- Low drain-source ON-resistance: $R_{DS(ON)} = 1.0 \Omega$ (typ.)
 - High forward transfer admittance: $|Y_{fs}| = 2.5 \text{ S}$ (typ.)
 - Low leakage current: $I_{DSS} = 10 \mu\text{A}$ (max) ($V_{DS} = 500 \text{ V}$)
 - Enhancement mode: $V_{th} = 2.4$ to 4.4 V ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	500	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	7	A
	Pulse (t = 1 ms) (Note 1)	I _{DP}	28	
Drain power dissipation (T _c = 25°C)		P _D	35	W
Single pulse avalanche energy (Note 2)		E _{AS}	129	mJ
Avalanche current		I _{AR}	7	A
Repetitive avalanche energy (Note 3)		E _{AR}	3.5	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55 to 150	°C



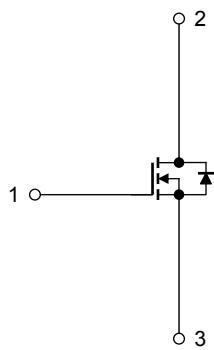
Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Internal Connection

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th} (ch-c)	3.57	°C/W
Thermal resistance, channel to ambient	R _{th} (ch-a)	62.5	°C/W



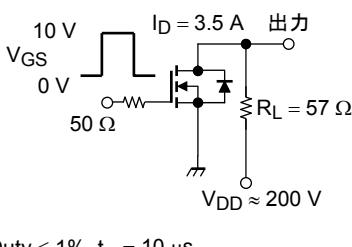
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD} = 90$ V, $T_{ch} = 25^\circ\text{C}$ (initial), $L = 4.5$ mH, $R_G = 25$ Ω , $I_{AR} = 7$ A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	—	—	±1	μA	
Drain cut-off current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	—	—	10	μA	
Drain-source breakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	500	—	—	V	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.4	—	4.4	V	
Drain-source ON-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 3.5 A	—	1.0	1.22	Ω	
Forward transfer admittance	Y _{fs}	V _{DS} = 10 V, I _D = 3.5 A	0.7	2.5	—	S	
Input capacitance	C _{iss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	—	600	—	pF	
Reverse transfer capacitance	C _{rss}		—	4	—		
Output capacitance	C _{oss}		—	70	—		
Switching time	Rise time	t _r	 10 V 0 V 50 Ω ID = 3.5 A 出力 VGS RL = 57 Ω VDD ≈ 200 V Duty ≤ 1%, tW = 10 μs	—	18	—	ns
	Turn-on time	t _{on}		—	40	—	
	Fall time	t _f		—	8	—	
	Turn-off time	t _{off}		—	55	—	
Total gate charge	Q _g	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 7 A	—	12	—	nC	
Gate-source charge	Q _{gs}		—	7	—		
Gate-drain charge	Q _{gd}		—	5	—		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	—	—	7	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	—	—	28	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 7 A, V _{GS} = 0 V	—	—	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 7 A, V _{GS} = 0 V, dI _{DR} /dt = 100 A/μs	—	1200	—	ns
Reverse recovery charge	Q _{rr}		—	7	—	μC

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